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PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	

Name	Execution Date
HIROTAKA OTAKE	06/26/2013
TOSHIO HANADA	06/26/2013

RECEIVING PARTY DATA

Name:	ROHM CO., LTD.	
Street Address:	21, SAIIN MIZOSAKI-CHO	
Internal Address:	UKYO-KU, KYOTO-SHI	
City:	КҮОТО	
State/Country:	JAPAN	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13950904

CORRESPONDENCE DATA

Fax Number:

Phone: 860-286-2929

Email: usptopatentmail@cantorcolburn.com

Correspondence will be sent via US Mail when the email attempt is unsuccessful.

Correspondent Name: CANTOR COLBURN LLP
Address Line 1: 20 CHURCH STREET

Address Line 2: 22ND FLOOR

Address Line 4: HARTFORD, CONNECTICUT 06103

ATTORNEY DOCKET NUMBER:	MIM0031USP
NAME OF SUBMITTER:	DANIEL P. LENT
Signature:	/Daniel P. Lent/
Date:	10/09/2013

Total Attachments: 2 source=6V41328#page1.tif source=6V41328#page2.tif

> PATENT REEL: 031373 FRAME: 0301

OF \$40.00 13950904

ASSIGNMENT

WHEREAS We, Hirotaka OTAKE of Kyoto, Japan and Toshio HANADA of Kyoto, Japan (hereinafter referred to as "ASSIGNORS") have invented certain new and useful improvements in:

POWER MODULE SEMICONDUCTOR DEVICE

which claims priority to **Japanese** Application No. 2012-111274, filed May 15, 2012, and **Japanese** Application No. 2012-165858, filed July 26, 2012, and for which I am about to file or have filed an application for Letters Patent of the United States:

AND WHEREAS, ROHM CO., LTD. (hereinafter referred to as "ASSIGNEE"), a corporation organized and existing under the laws of the Country of Japan, having a place of business at 21, Saiin Mizosaki-cho Ukyo-ku, Kyoto-shi, Kyoto, Japan, is desirous of acquiring an interest in the United States and all foreign countries, in and to the said invention and Letters Patent to be obtained therefor;

NOW THEREFORE, TO ALL WHOM IT MAY CONCERN, be it known that, for good and valuable consideration, the receipt of which is hereby acknowledged, We, the said ASSIGNORS have assigned and transferred, and hereby assign and transfer unto the said ASSIGNEE, the entire right, title and interest in and to said invention in the United States and in all foreign countries, including priority rights, as fully set forth and described in said application; and We do hereby authorize and request the Commissioner of Patents to issue said Letters Patent on said application, and any and all Letters Patent that may be issued upon any and all revivals, refilings, continuations, continuations-in-part, divisions and reissues thereof, to the said ASSIGNEE, an assignee of the entire right, title and interest in and to the same, for the sole use and behoof of ASSIGNEE, its successors and assigns; and We do hereby agree that the said ASSIGNEE, may apply for foreign Letters Patent on said invention and that We will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by the said ASSIGNEE, its successors or assigns, and that We will, at the cost and expense of the said ASSIGNEE fully assist and cooperate in all matters in connection with the United States and foreign applications and patents issuing thereon.

PATENT REEL: 031373 FRAME: 0302 The undersigned declare that all statements made herein of their own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Date:	June 26, 2013	Hirotaka Otake	L.S
	_	Hirotaka OTAKE	
Date:	June 26. 2013	Toshio Hanada	L.S
	_	Toshio HANADA	